Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	0	"10806644".ap.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:05
S2	3	"806644".ap.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:07
S3	14	"goudarzi, vahid".in.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:09
S4	4	(("5411199") or ("5167361")).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/04 15:23
S5	95	"motorola".as. and shield and substrate and "method".ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:26
S6	5	"motorola".as. and shield.ti. and substrate and "method".ti.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:32
S7	1	"conductive shield track"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:33
S8	132	"shield track"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/17 14:28

S9	132	solder and ("over printing" or overprinting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:54
S10	38	solder with ("over printing" or overprinting)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/04 15:54
S11	2	("5411199").URPN.	USPAT	OR	ON	2005/05/04 16:22
S12	1	shield with (solder adj clad\$4)	USPAT	OR	ON	2005/05/05 09:21
S13	534	(257/667).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/05 09:40
S14	1227	(257/704).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/05 10:05
S15	359	(257/710).CCLS.	US-PGPUB; USPAT; USOCR; EPO; DERWENT; IBM_TDB	OR	OFF	2005/05/05 13:47
S16	4437	solder and flux and dip\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 13:49
S17	1470	solder and (flux with dip\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 13:49
S18	1003	solder with (flux with dip\$4)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 13:50

S19	842	solder with (flux with (dipped or dipping))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 13:50
S20	497	solder with (flux with dipped)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/05 13:50
S22	, 2	"shield track" and (cladding or cladded)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/17 15:18
S23	4915	(emi or rfi) with (seal or shield)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/17 15:18
S24	162	(emi or rfi) with (seal or shield) and clad\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/11/17 15:19
S25	8	("3649803" "4339628" "5357404" "5358774" "5371404").PN. OR ("5411199"). URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/11/17 15:27

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S26	54	(US-20040172502-\$ or	US-PGPUB;	OR	ON	2006/06/29 16:16
		US-20040046245-\$ or	USPAT			
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